

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Presently Amended) A heat conductive polishing pad for chemical-mechanical polishing comprising:

a polishing body including a thermoconductive polymer having a substrate with filler particles contained therein wherein said filler particles contain a Group II salt comprising magnesium.

2. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said polishing body further includes a base pad and said thermoconductive polymer forms a polishing surface located over said base pad and said thermoconductive polymer has a thermal conductivity of greater than about 1 Watts m⁻¹ K⁻¹ and an electrical volume resistivity of greater than about 1 x 10¹⁵ ohm cm⁻¹ at 25°C.

3. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said substrate is selected from the group consisting of:

polyurethane;

polyolefin; and

polyvinyl esters.

4. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said substrate is selected from the group consisting of:

polyurea;
polycarbonate;
aliphatic polyketone;
polysulfone;
aromatic polyketone;
6,6 nylon;
6,12 nylon; and
polyamide.

5. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said substrate is selected from the group consisting of:

thermoplastic rubber; and
melt-processible rubber.

6. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said substrate is selected from the group consisting of:

polypropylene;
polyethylene;
crosslinked polyethylene;
ethylene vinyl acetate; and

polyvinylacetate.

7. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said thermoconductive polymer has a grafted compound located substantially throughout said polymer.

8. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said thermoconductive polymer has a modified surface and a grafted surface on said modified surface, said grafted surface comprising a grafted compound.

9. (Original) The heat conductive polishing pad as recited in Claim 7 wherein said grafted compound includes an inorganic metal oxide.

10. (Original) The heat conductive polishing pad as recited in Claim 8 wherein said grafted compound includes an inorganic metal oxide.

11. (Original) The heat conductive polishing pad as recited in Claim 7 wherein said thermoconductive polymer has a foam structure and said grafted compound includes a controlled watability compound.

12. (Original) The heat conductive polishing pad as recited in Claim 8 wherein said thermoconductive polymer has a foam structure and said grafted compound includes a controlled watability compound.

13. (Original) The heat conductive polishing pad as recited in Claim 7 wherein said grafted compound includes an organic compound.

14. (Original) The heat conductive polishing pad as recited in Claim 8 wherein said grafted compound includes an organic compound.

15. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said Group II salt includes an anion selected from the group consisting of:

Sulfate;

Stearate; and

Carbonate.

16. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said Group II salt includes an anion comprised of oxide.

17. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said Group II salt is Magnesium Oxide.

18. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said Group II salt includes an anion comprised of hydroxide.

19. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said filler particles comprise at least about 20% by weight of said thermoconductive polymer.

20. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said filler particles have a spherical shape having an average diameter of less than about 50 μm to about 1 μm .

21. (Original) The heat conductive polishing pad as recited in Claim 1 wherein said filler particles are incorporated substantially throughout said substrate.

Claims 22-28 (withdrawn)

Claims 29-30 (withdrawn)